**PACKAGE** 

SOT-23



## **MMBD701**

3

5HF

TO-236AB (Low)

#### **CONNECTION DIAGRAM**



### **Schottky Barrier Diode**

Sourced from Process GE

Absolute Maximum Ratings\* TA = 25°C unless otherwise noted

Sym	Parameter	Value	Units
$T_{stg}$	Storage Temperature	-55 to +150	°C
TJ	Operating Junction Temperature	-55 to +125	οС
Wiv	Working Inverse Voltage	35	V
$P_{F}$	Forward Power Dissipation @ T <sub>A</sub> = 25°C	200	mW
	Derate above 25 <sup>o</sup> C	2.0	Mw/ <sup>o</sup> C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

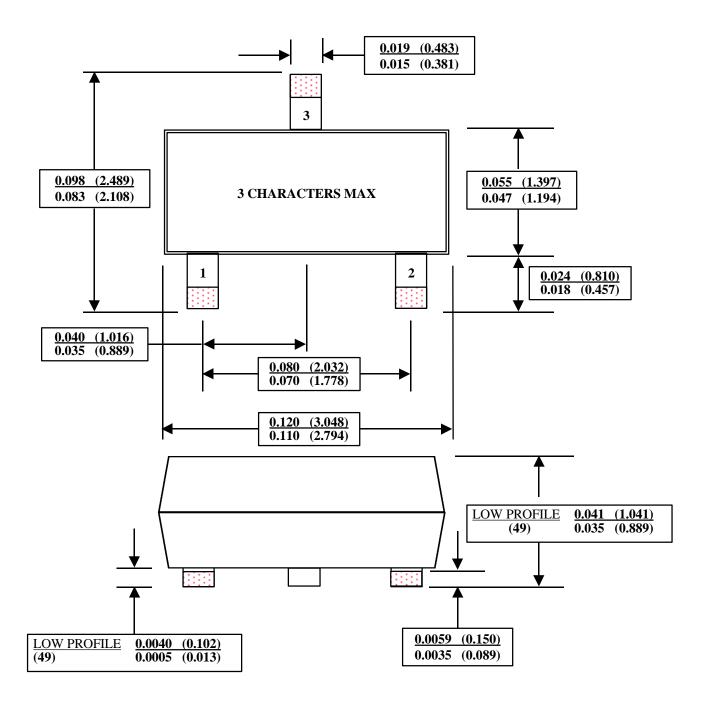
# ADVANCED INFORMATION ONLY NOT IN PRODUCTION

**Electrical Characteristics** 

TA = 25°C unless otherwise noted

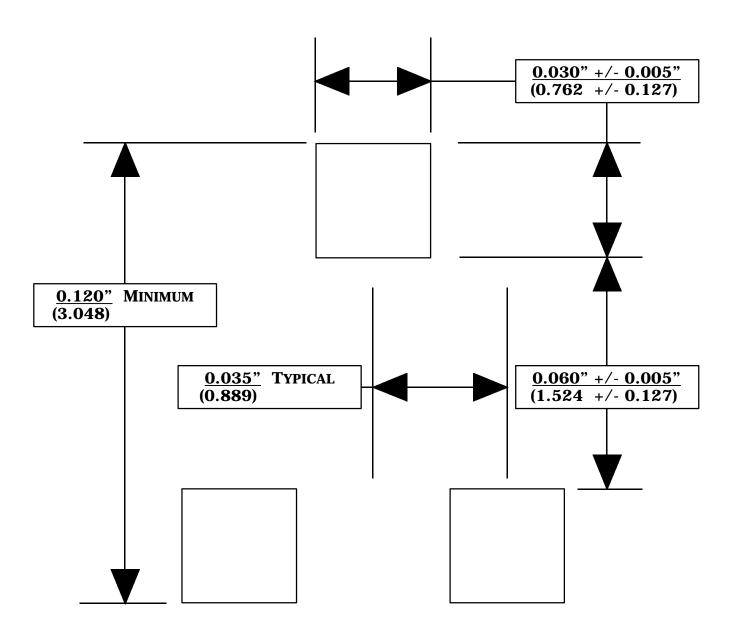
SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B <sub>V</sub> Breakdown Voltage		70		V	$I_R = 10 \text{ uA}$
I <sub>R</sub> Reverse Leakage			200	nA	V <sub>R</sub> = 35 V
V <sub>F</sub> Forward Voltage <i>→</i>			500 1.0	mV V	$I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$
**Capacitance			1.0	pF	$V_{R} = 20 V$ f = 1.0 MHz





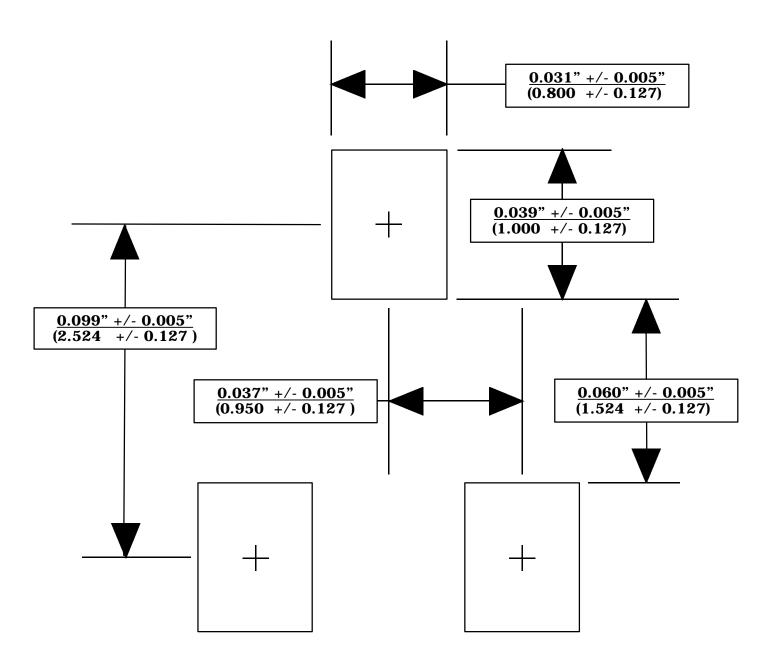






RECOMMENDED SOLDER PADS FOR SOT-23





RECOMMENDED SOLDER PADS
FOR
U.S. & European SOT-23
&
Japanese SC-59

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#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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